

MAXIMUM RATINGS (Above which the useful life may be impaired)

Storage Temperature	-65°C to +150
Temperature (Ambient) Under Bias	-55°C to +125°C
Supply Voltage to Ground Potential (Pin 16 to Pin 8) Continuous	-0.5 V to +8
DC Voltage Applied to Outputs for High Output State	-0.5 V to +V _{CC} m
DC Input Voltage	-0.5 V to +5.5
Output Current Into Outputs When Output is LOW	50 mA
DC Input Current	-30 mA to +5 mA

ELECTRICAL CHARACTERISTICS

Am260250/960250X T_A = 0°C to +75°C V_{CC} = 4.75 to 5.25 V (COM grade)
 Am260251/960251X T_A = -55°C to +125°C V_{CC} = 4.50 to 5.50 V (MIL grade)

DC Characteristics Over Operating Range (Note 1)

Parameters	Operating Range	Test Conditions	LIMITS						Units		
			T _A = MIN		T _A = +25°C		T _A = MAX				
			Min	Max	Min	Typ	Max	Min	Max		
V _{OH} Output HIGH Voltage	MIL or COM	V _{CC} = MIN., I _{OH} = -0.96 mA	2.40		2.40	3.6		2.40		Volt	
V _{OL} Output LOW Voltage	MIL	I _{OL} = 8 x I _{IL} MAX.		0.40		0.2	0.40		0.40	Volt	
	COM	I _{OL} = 8 x I _{IL} MAX.		0.45		0.2	0.45		0.45		
V _{IH} Input HIGH Voltage	MIL		2.00		1.70			1.50		Volt	
	COM		1.90		1.80			1.60			
V _{IL} Input LOW Voltage	MIL		0.85				0.90		0.85	Volt	
	COM		0.85				0.85		0.85		
I _{IL} Input Load Current	MIL	V _{IN} = 0.40 V	V _{CC} = MAX.	-1.60		-1.10	-1.60		-1.60	mA	
			V _{CC} = MIN.	-1.24		-0.97	-1.24		-1.24		
	COM	V _{IN} = 0.45 V	V _{CC} = MAX.	-1.60		-1.00	-1.60		-1.60		
			V _{CC} = MIN.	-1.41		-0.90	-1.41		-1.41		
I _{IH} Reverse Input Current	MIL or COM	V _{CC} = MAX., V _{IN} = 4.5 V		60		2	60		60	μA	
I _{SC} Short Circuit Current	MIL	V _{CC} = 5.0 V, V _O = 1.0 V			-8		-25			mA	
	COM	V _{CC} = 5.0 V, V _O = 1.0 V			-8		-35				
I _{DD} Power Supply Current	9602 MIL	V _{CC} = 5.0 V	GND Pins 5 and 11 R _X = 10 kΩ		45		35	45		45	mA
					52		35	50		52	
	2602 COM	V _{CC} = MAX.	GND Pins 5 and 11 R _X = 10 kΩ		56		35	56		56	

Switching Characteristics (T_A = 25°C)

Parameters	Test Conditions	2602 9602 MIL			9602 COM			Units	
		Min	Typ	Max	Min	Typ	Max		
t _{pd+}	Turn Off Delay Negative Trigger Input to True Output		25	35	25	40		ns	
t _{pd-}	Turn On Delay Negative Trigger Input to False Output	V _{CC} = 5.0 V, C _L = 15 pF	25	35	25	40		ns	
t _{pw} (min)	Minimum Output Pulse Width	True Output (Q)	R _X = 5 kΩ, C _X = 0 pF	45	65	50	70		ns
			False Output (Q)	55	75	60	80		
t _{pw}	Pulse Width	V _{CC} = 5.0 V, C _L = 15 pF R _X = 10 kΩ, C _X = 1000 pF	3.08	3.42	3.76	3.08	3.42	3.76	μs
R _X	Timing Resistor over Temperature Range (Note 2)		5	50	5	50		kΩ	
t _{pd-} (C _D)	Delay from C _D to Q output LOW		11	17	11	17		ns	
Am2602			Min	Typ	Max				
Δt _{pw} (T)	Maximum change in Pulse Width True Output over temperature range 0°C to +75°C	V _{CC} = 5.0 V, C _L = 15 pF R _X = 10 kΩ, C _X = 1000 pF						%	
	Maximum change in Pulse Width True Output over temperature range -55°C to +125°C (Am2602 MIL)				4.0	7.0			

Notes: 1. Tests are conducted with a 10 kΩ resistor placed between Pin 2 (14) and V_{CC} unless otherwise noted.

2. Maximum permissible R_X when used below 0°C is 25 kΩ.

OPERATION RULES

1. An external resistor R_x and an external capacitor C_x are required as shown in the logic diagram. The values of R_x may vary from 5.0 k Ω to 50 k Ω for 0°C to +75°C operation and 5.0 k Ω to 25 k Ω for -55°C to +125°C operation. C_x may vary from 0 to any value necessary and obtainable.
2. If a fixed value of R_x is used, the following values are recommended: $R_x = 30$ k Ω for 0°C to +75°C operation; $R_x = 10$ k Ω for -55°C to +125°C operation.

3. The output pulse width T is defined as follows:

$$T = 0.32 R_x C_x \left[1 + \frac{0.7}{R_x} \right] \quad \text{(For } C_x \text{ greater than } 10^3 \text{ pF)} \quad \text{Where: } R_x \text{ is in k}\Omega, C_x \text{ is in pF, } T \text{ is in ns. For } C_x < 10^3 \text{ pF see Fig. 2}$$

4. If electrolytic type capacitors are to be used, it is recommended that they have low leakage. For capacitors with a high reverse leakage the following circuits can be used:



$$R < 0.6 R_x \text{ (Max)}$$

D_1 : any silicon type diode, such as FD700



This circuit also allows larger value of R to be used for longer output pulse width.

$$R < R_1 (0.7) (h_{FE} Q)$$

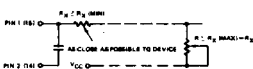
$$R_1 (\text{min}) < R_x < R_1 (\text{max})$$

Q_1 : Any NPN silicon device with sufficient h_{FE} at low currents, such as 2N2511

Both circuits prevent reverse voltage across C_x . The pulse width T for the circuits is defined as follows:

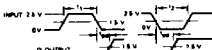
$$T \approx 0.30 RC_x \left[1 + \frac{0.7}{R} \right] \quad \text{Where: } R \text{ is in k}\Omega, C_x \text{ is in pF, } T \text{ is in ns.}$$

5. To obtain variable pulse width, by remote trimming, the following circuit is recommended.

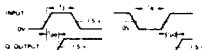


6. Under any operating condition, C_x and R_x (min) must be kept as close to the circuit as possible to minimize stray capacitance and reduce noise pickup.
7. Input Trigger Pulse Rules.

Input to Pin 5 (11)
Pin 4 (12) = LOW
Pin 3 (13) = HIGH



Input to Pin 4 (12)
Pin 5 (11) = HIGH
Pin 3 (13) = HIGH



8. The retriggerable pulse width is calculated as shown below:

$$t_w = t_{pw} + t_{del} = 0.32 R_x C_x \left(1 + \frac{0.7}{R_x} \right) + t_{del}$$

The retrigger pulse width is equal to the pulse width t_{pw} plus a delay time. For pulse widths greater than 500 ns, t_w can be approximated as t_{pw} .

NOTE: Retriggling will not occur if the retrigger pulse comes within $0.32 R_x C_x \left(1 + \frac{0.7}{R_x} \right)$ ns after the initial trigger pulse.

9. Reset Operation — The Am2602/9602 have an active LOW reset facility. By applying a low to the reset input, any timing cycle can be terminate if or any new cycle inhibited until the low reset input is removed. Trigger inputs will not produce spikes in the output when the reset is held low.

DEFINITION OF TERMS

SUBSCRIPT TERMS:

- H HIGH, applying to a HIGH logic level or when used with V_{CC} to indicate high V_{CC} value.
- I Input.
- L LOW, applying to LOW logic level or when used with V_{CC} to indicate low V_{CC} value.
- O Output.

OPERATIONAL TERMS:

- I_{IL} Forward input load current.
- I_{OH} Output HIGH current, forced out of output in V_{OH} test.
- I_{OL} Output LOW current, forced into the output in V_{OL} test.
- I_{RH} Reverse input load current.
- Negative Current** Current flowing out of the device.
- Positive Current** Current flowing into the device.
- V_{IH} Minimum logic HIGH input voltage. Refer to figure 2.
- V_{IL} Maximum logic LOW input voltage. Refer to figure 2.
- V_{OH} Minimum logic HIGH output voltage with output HIGH current I_{OH} flowing out of output.
- V_{OL} Maximum logic LOW output voltage with output LOW current I_{OL} into output.

FUNCTIONAL TERMS:

- \bar{C}_0 The asynchronous direct clear input. A LOW on this input resets the monostable independent of other conditions.
- Fan-Out** The logic HIGH or LOW output drive capability in terms of Input Unit Loads.
- \bar{I}_0 The active LOW input of the monostables. With input I, LOW a HIGH to LOW transition on \bar{I}_0 will cause triggering.
- I_1 The active HIGH input of the monostables. With \bar{I}_1 HIGH a LOW to HIGH transition on I_1 will cause triggering.
- Input Unit Load** One TTL gate input load.
- Q** The TRUE output of the monostables.
- \bar{Q} The FALSE output of the monostables.
- Triggering** The switching of the monostable from the stable state to the unstable state and start of the timing cycle.

SWITCHING TERMS:

- t_{pd+} The propagation delay from a HIGH to LOW transition on \bar{I}_0 to the true (Q) output LOW to HIGH transition.
- t_{pd-} The propagation delay from a HIGH to LOW transition on \bar{I}_0 to the false (\bar{Q}) output HIGH to LOW transition.
- $t_{pL}(\text{min})$ The minimum true (Q) output pulse width with $R_x = 5$ k Ω , $C_x = 0$ pF.
- t_{pw} The pulse width obtained with $R_x = 10$ k Ω , $C_x = 1000$ pF.
- $\Delta t_{pw}(T)$ The maximum percentage change in pulse width of the true (Q) output for the Am2602 over the temperature range from the pulse width at 25°C.

Am 2602
Normalized Output
Pulse Width Versus
Ambient Temperature

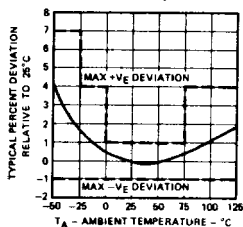
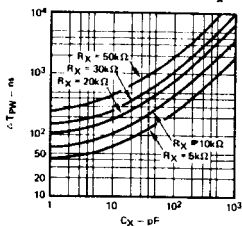


Figure 1

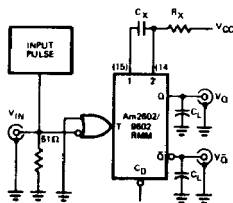
Output Pulse Width (ΔT_{PW})
Using Low Values of C_X



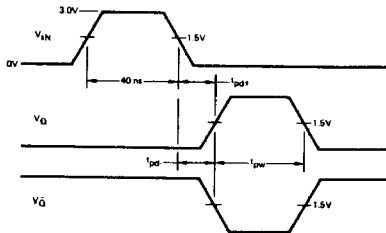
NOTE: Above $C_X = 10^3$ pF Use $\Delta T_{PW} = 0.32 C_X R_X (1+0.7/R_X)$

Figure 2

SWITCHING TIME TEST CIRCUIT AND WAVEFORMS



$V_{CC} = \text{Pin } 18$
 $\text{Gnd.} = \text{Pin } 8$



INPUT PULSE
 $f = 100 \text{ kHz}$
 $C_D = 5 \text{ pF}$
 $\text{Width} = 40 \text{ ns}$
 $t_r = t_f \leq 10 \text{ ns}$

Figure 3

TRUTH TABLE
Am2602/9602
For Each Monostable

\bar{I}_b	I_i	\bar{C}_D	Operation
H→L	L	H	Trigger
H	L→H	H	Trigger
X	X	L	Reset

H = HIGH Voltage Level
L = LOW Voltage Level
X = Don't Care
H→L = HIGH to LOW Voltage Level transition
L→H = LOW to HIGH Voltage Level transition

Table I

MSI INTERFACING RULES

Interfacing Digital Family	Equivalent Input Unit Load	
	HIGH	LOW
Advanced Micro Devices 9300/2500 Series	1	1
FSC Series 9300	1	1
Ti Series 54/7400	1	1
Signetics Series 8200	2	2
National Series DM 75/85	1	1
DTL Series 930	12	1

Table III

Am2602/9602 LOADING RULES

Input/Output	Pin No.'s	Input Unit Load	Fanout	
			Output HIGH	Output LOW
Monostable 1	C_x	1	—	—
	$C_x R_x$	2	—	—
	\bar{C}_D	3	1	—
	I_i	4	1	—
	\bar{I}_b	5	1	—
	Q	6	—	16
	\bar{Q}	7	—	16
	GND	8	—	—
Monostable 2	\bar{Q}	9	—	16
	Q	10	—	16
	\bar{I}_b	11	1	—
	I_i	12	1	—
	\bar{C}_D	13	1	—
	$C_x R_x$	14	—	—
	C_x	15	—	—
	V_{CC}	16	—	—

Table II

INPUT/OUTPUT INTERFACE CONDITIONS

Voltage Interface Conditions — LOW & HIGH

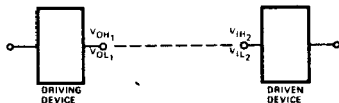
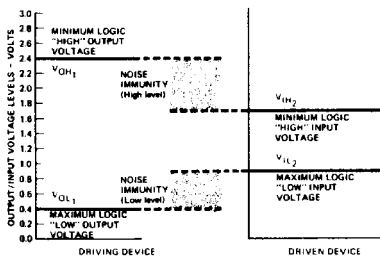
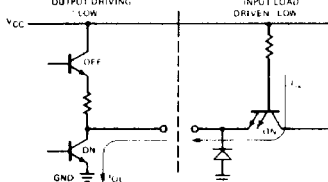
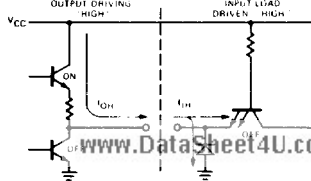


Figure 4

Current Interface Conditions — LOW

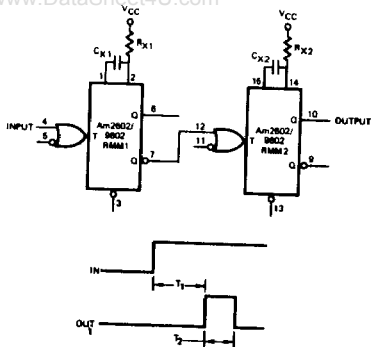


Current Interface Conditions — HIGH



Am2602/9602 APPLICATIONS

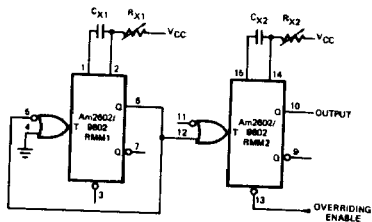
www.DataSheet4U.com



Delayed Pulse Generation

Figure 5

The first monostable determines the time T_1 before the initiation of the output pulse. The second monostable determines T_2 , the output pulse width.



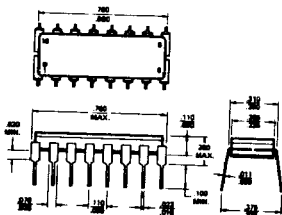
Pulse Generator

Figure 6

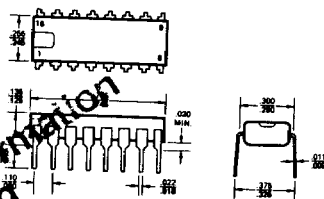
The output frequency produced with the above configuration is determined by C_{X1} and R_{X1} , while the pulse width is determined by C_{X2} and R_{X2} . Monostable 1 forms an astable multivibrator with an output pulse width of approximately 25 ns, while monostable 2 extends the pulse width to the required value.

PHYSICAL DIMENSIONS Dual-In-Line

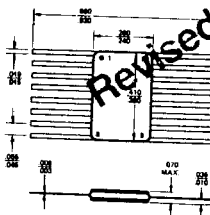
Hermetic



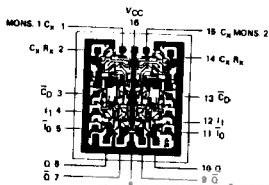
Molded



Flat Package



Metalization and Pad Layout



www.DataSheet4U.com

82 x 71 Max



**ADVANCED
MICRO
DEVICES INC.**
901 Thompson Place
Sunnyvale
California 94088
(408) 732-2400
TWX: 910-339-9290
TELEX: 34-6306

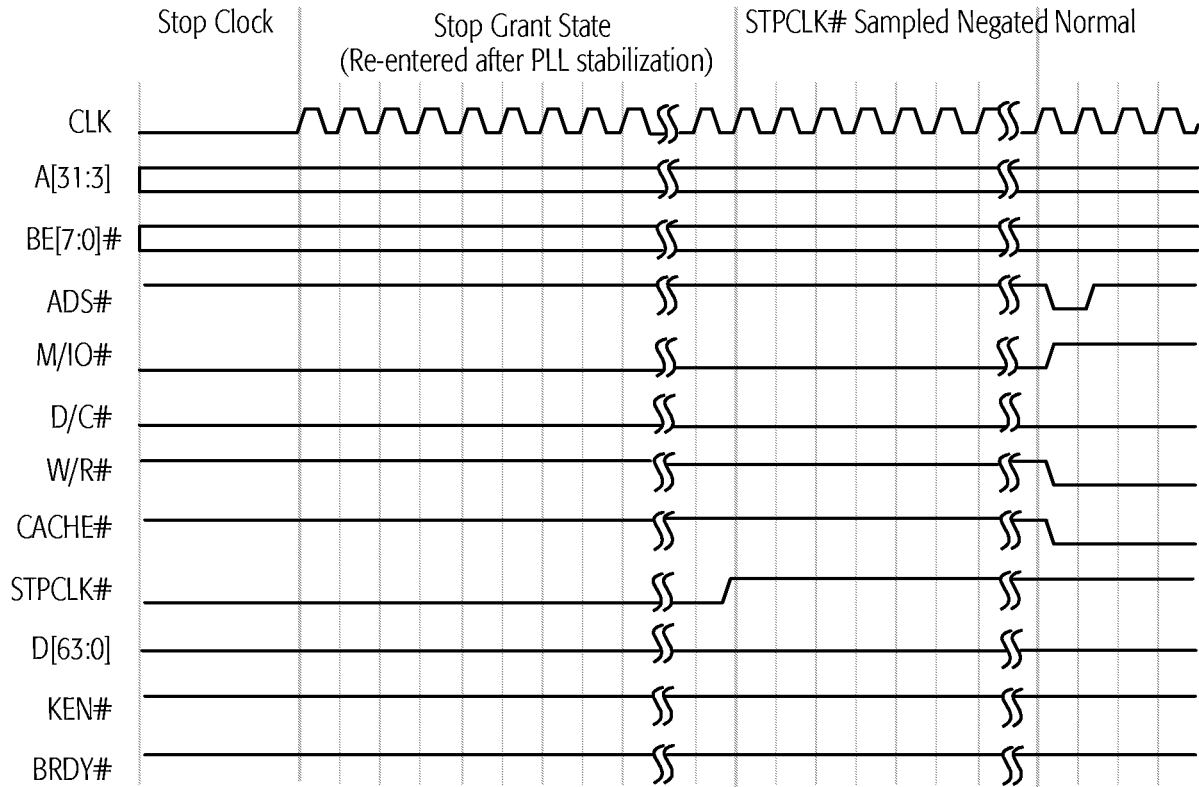


Figure 75. Stop Grant and Stop Clock Modes, Part 2

**INIT-Initiated
Transition from
Protected Mode to
Real Mode**

INIT is typically asserted in response to a BIOS interrupt that writes to an I/O port. This interrupt is often in response to a Ctrl-Alt-Del keyboard input. The BIOS writes to a port (similar to port 64h in the keyboard controller) that asserts INIT. INIT is also used to support 80286 software that must return to Real mode after accessing extended memory in Protected mode.

The assertion of INIT causes the processor to empty its pipelines, initialize most of its internal state, and branch to address FFFF_FFF0h—the same instruction execution starting point used after RESET. Unlike RESET, the processor preserves the contents of its caches, the floating-point state, the MMX state, Model-Specific Registers (MSRs), the CD and NW bits of the CR0 register, the time stamp counter, and other specific internal resources.

Figure 76 shows an example in which the operating system writes to an I/O port, causing the system logic to assert INIT. The sampling of INIT asserted starts an extended microcode sequence that terminates with a code fetch from FFFF_FFF0h, the reset location. INIT is sampled on every clock edge but is not recognized until the next instruction boundary. During an I/O write cycle, it must be sampled asserted a minimum of three clock edges before BRDY# is sampled asserted if it is to be recognized on the boundary between the I/O write instruction and the following instruction. If INIT is asserted synchronously, it can be asserted for a minimum of one clock. If it is asserted asynchronously, it must have been negated for a minimum of two clocks, followed by an assertion of a minimum of two clocks.

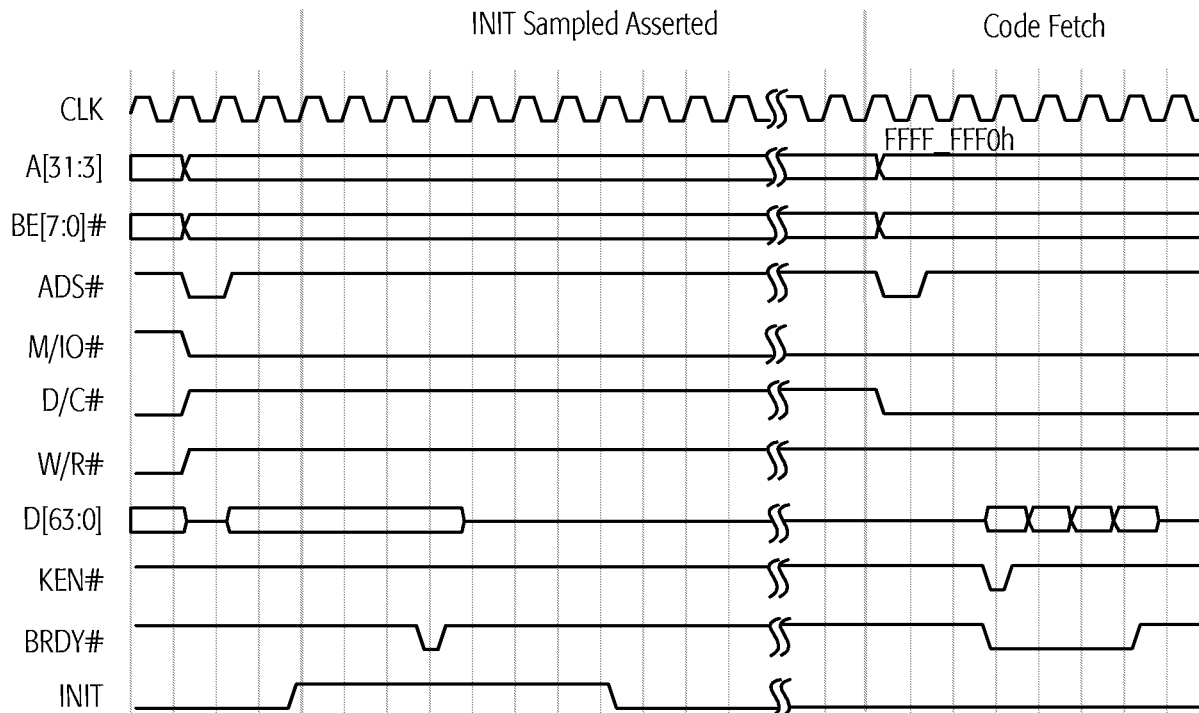


Figure 76. INIT-Initiated Transition from Protected Mode to Real Mode



6 Power-on Configuration and Initialization

On power-on the system logic must reset the AMD-K6-2 processor by asserting the RESET signal. When the processor samples RESET asserted, it immediately flushes and initializes all internal resources and its internal state, including its pipelines and caches, the floating-point state, the MMX and 3DNow! states, and all registers. Then the processor jumps to address FFFF_FFF0h to start instruction execution.

6.1 Signals Sampled During the Falling Transition of RESET

FLUSH# FLUSH# is sampled on the falling transition of RESET to determine if the processor begins normal instruction execution or enters Tri-State Test mode. If FLUSH# is High during the falling transition of RESET, the processor unconditionally runs its Built-In Self Test (BIST), performs the normal reset functions, then jumps to address FFFF_FFF0h to start instruction execution. (See “Built-In Self-Test (BIST)” on page 217 for more details.) If FLUSH# is Low during the falling transition of RESET, the processor enters Tri-State Test mode. (See “Tri-State Test Mode” on page 218 and “FLUSH# (Cache Flush)” on page 103 for more details.)

BF[2:0] The internal operating frequency of the processor is determined by the state of the bus frequency signals BF[2:0] when they are sampled during the falling transition of RESET. The frequency of the CLK input signal is multiplied internally by a ratio defined by BF[2:0]. (See “BF[2:0] (Bus Frequency)” on page 92 for the processor-clock to bus-clock ratios.)

BRDYC# BRDYC# is sampled on the falling transition of RESET to configure the drive strength of A[20:3], ADS#, HITM#, and W/R#. If BRDYC# is Low during the fall of RESET, these outputs are configured using higher drive strengths than the standard strength. If BRDYC# is High during the fall of RESET, the standard strength is selected. (See “BRDYC# (Burst Ready Copy)” on page 95 for more details.)

6.2 RESET Requirements

During the initial power-on reset of the processor, RESET must remain asserted for a minimum of 1.0 ms after CLK and V_{CC} reach specification. (See “CLK Switching Characteristics” on page 255 for clock specifications. See “Electrical Data” on page 247 for V_{CC} specifications.)

During a warm reset while CLK and V_{CC} are within specification, RESET must remain asserted for a minimum of 15 clocks prior to its negation.

6.3 State of Processor After RESET

Output Signals

Table 31 shows the state of all processor outputs and bidirectional signals immediately after RESET is sampled asserted.

Table 31. Output Signal State After RESET

Signal	State	Signal	State
A[31:3], AP	Floating	LOCK#	High
ADS#, ADSC#	High	M/IO#	Low
APCHK#	High	PCD	Low
BE[7:0]#	Floating	PCHK#	High
BREQ	Low	PWT	Low
CACHE#	High	SCYC	Low
D/C#	Low	SMIACT#	High
D[63:0], DP[7:0]	Floating	TDO	Floating
FERR#	High	VCC2DET	Low
HIT#	High	VCC2H/L#	Low
HITM#	High	W/R#	Low
HLDA	Low	—	—

Registers

Table 32 on page 175 shows the state of all architecture registers and Model-Specific Registers (MSRs) after the processor has completed its initialization due to the recognition of the assertion of RESET.